

METHOD FOR PLATING WIRING BOARD, AND WIRING BOARD

ABSTRACT

5 There are provided a method for plating a wiring board,
characterized in that: in order to selectively plate a
plating target area on the wiring board having a circuit
pattern having an unevenness of 25 μm or more formed on an
insulating substrate, when areas other than the plating
10 target area are masked, using a masking film obtained by
sequentially laminating an adhesive layer and a release
sheet on one surface of a polybutylene terephthalate film;
removing the release sheet of the masking film; then, bonding
the adhesive layer surface of the masking film to a
15 predetermined area on the wiring board under an environment
at room temperature, followed by thermocompression bonding;
and then, plating the plating target area; and a wiring board
using the method. An area not to be plated is not plated
by entry of a plating solution even if the wiring board has
20 a large unevenness is the circuit pattern. Furthermore,
punching workability of the masking film, and, in particular,
generation of a burr, unsuccessful hole-making, and the like
is inhibited.

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(Figure 2)